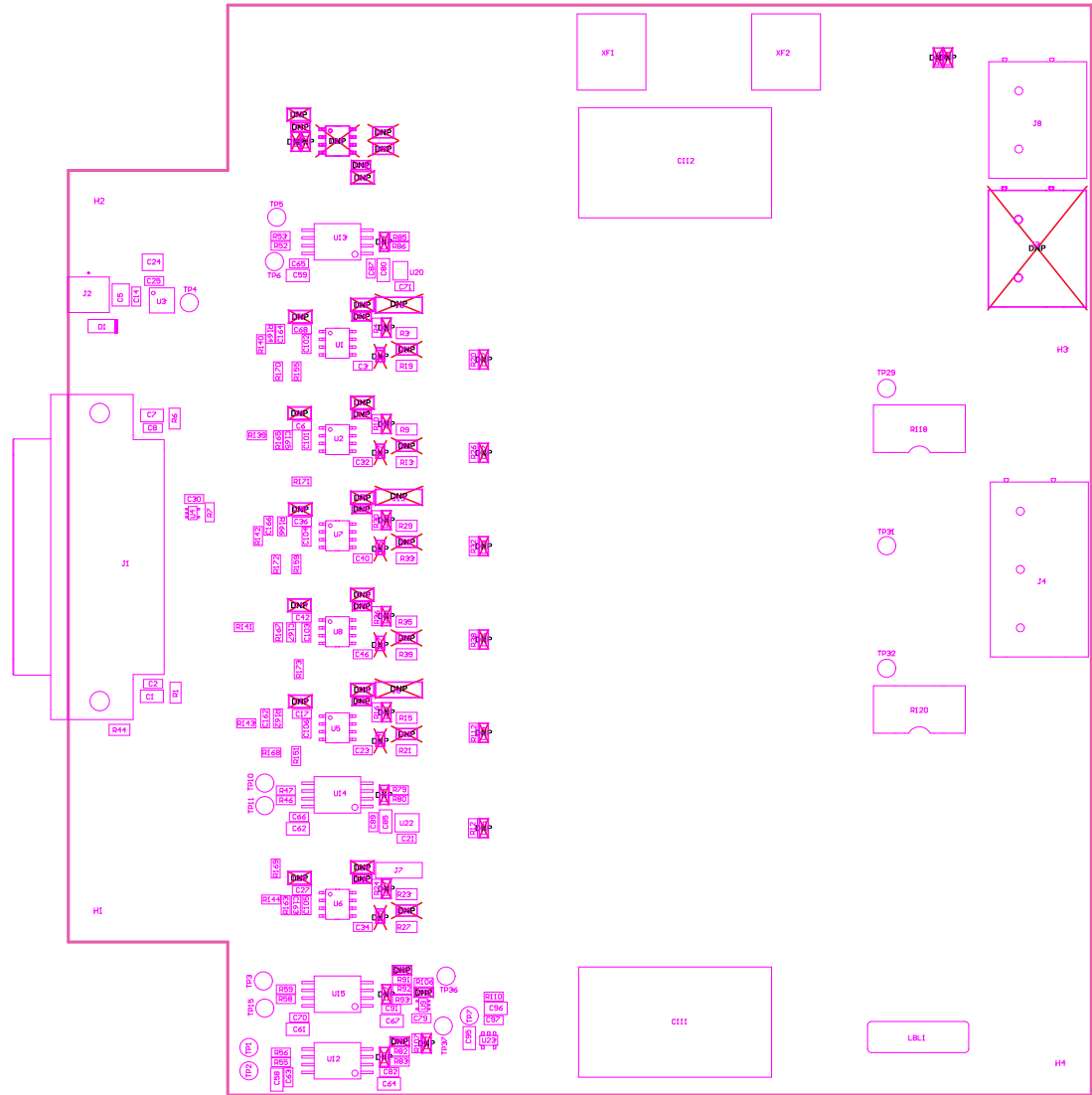


- Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be in the Label Table in the PDF schematic.
- Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

ALL PARTWORK VIEWED FROM TOP SIDE	BOM# #: T10A-01420	REV: E1	SUN REV: Not In versionControl
LAYER NAME = MB Assembly Top	T10 #: T10A-01420		
Top Assembly Drawing	GENERATED: 1 5/11/2017	11:12:36 AM	TEXAS INSTRUMENTS



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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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